



RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 1725  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q85154

Takuo FUNAYA, et al.

Appln. No.: 10/516,708

Group Art Unit: 1725

Confirmation No.: 6730

Examiner: Lynne Renee Edmondson

Filed: December 3, 2004

For: SOLDER AND PACKAGE USING THE SAME

**RESPONSE UNDER 37 C.F.R. § 1.116**

**MAIL STOP AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated September 25, 2006, please consider the remarks as submitted herewith on the accompanying pages.

**REMARKS**

Claims 9-13 and 15-36 are all the claims pending in the application.

Claims 9-13 and 15-36 have been rejected under 35 U.S.C. § 103, as allegedly being unpatentable over U.S. Published Application No. 2006/0071051 to Shoji *et al.* ("Shoji '051") in view of U.S. Patent No. 4,180,415 to Hampl ("Hampl '415").

Claims 9, 15, 21, and 27 recite that the silver is present in the claimed solder at X weight %, wherein X is equal to or greater than 0.001, but smaller than 0.1.